

# UNITED STATES PATENT AND TRADEMARK OFFICE

*cen*  
UNITED STATES DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office  
Address: COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, Virginia 22313-1450  
www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/873,976	06/01/2001	Anthony J. Cooper	508-039.7-1	3295
4955 7590 05/18/2007 WARE FRESSOLA VAN DER SLUYS & ADOLPHSON, LLP BRADFORD GREEN, BUILDING 5 755 MAIN STREET, P O BOX 224 MONROE, CT 06468			EXAMINER TRAN, THANH Y	
			ART UNIT 2822	PAPER NUMBER
			MAIL DATE 05/18/2007	DELIVERY MODE PAPER

**Please find below and/or attached an Office communication concerning this application or proceeding.**

The time period for reply, if any, is set in the attached communication.



## DETAILED ACTION

### *Claim Rejections - 35 USC § 103*

1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

2. Claims 53, 57, 58 and 59 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chan et al (U.S. 6,410,985) in view of Desai et al (U.S. 6,266,249).

As to claim 53, Chan et al discloses in figures 1F and 1H an electronic component to have an electrical component incorporated thereon, the electronic component comprising: a substrate (102) having at least a front substrate layer (112) with a front surface for receiving the electrical component; characterized in that the electrical component further comprising: grooves (114) provided in the front surface of the substrate (102) with separate conductive lines (118, figure 1H) where each conductive line (118) completely fills a groove of the grooves (114), the conductive lines (118) for electrical connection to the electrical component.

The limitation of “for electrical connection to the electrical component”, as recited above in the claim, is the intended use language, and it does not add any appreciable weight to the claim above. Furthermore, since the prior art reference recites the same structure as in the applicant’s claim, the reference is seen by the examiner as being capable of performing the same intended use.

Chan et al does not disclose conductive vias provided through the substrate for electrical connection to the electrical component.

Desai et al discloses in figures 2a-3b an electronic component comprising: conductive vias (18) provided through the substrate (16) for electrical connection to the electrical component (30) (see col. 3, lines 19-39). Therefore, it would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the electronic component of Chan et al by having conductive vias provided through the substrate as taught by Desai et al for electrically coupling substrate vias to corresponding bonding pads of the electrical component (integrated circuit) in order to provide electrical connection between the substrate and the chip (electrical component) (see col. 3, lines 19-39).

As to claims 57, 58 and 59, Chan et al discloses in figures 1F and 1H an electronic component, wherein the conductive lines (118) are metal ("silver interconnects" 118). The limitations of "the conductive lines are of metal deposited by sputtering" in claim 57, "the conductive lines are of metal deposited by vacuum deposition" in claim 58, and "the conductive lines are a fired slurry deposition" in claim 59 are process limitations in the product claims, which product does not otherwise patentably distinguish over prior art, cannot impart patentability to the product. In re Stephens 145 USPQ 656 (CCPA 1965).

### ***Claim Rejections - 35 USC § 103***

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person

having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 54-56 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chan et al (U.S. 6,410,985) in view of Desai et al (U.S. 6,266,249) as applied to claim 53 above, and further in view of Berkely et al (U.S. 6,031,729).

As to claims 54, 55, and 56, Chan et al in view of Desai et al does not disclose the front substrate layer is ceramic; and the grooves are formed by serration of a tape-casing, doctor blade or chemical etching. However, Berkely discloses in figure 4 a ceramic substrate having a front substrate layer (33). Therefore, it would have been obvious to a person having ordinary skill in the art at the time the invention was made to modify the electronic component of Chan et al by using a ceramic material for a front layer of the substrate as taught by Berkely. One of ordinary skill in the art would have been motivated because ceramic material is a high temperature material and could be used for supporting the chip component mounted on the substrate; and the ceramic material also has a low production cost. The limitations of “the grooves are formed by serration of a tape-casing, doctor blade” in claim 54; “the grooves are formed by laser cutting” in claim 55; and “the grooves are formed by chemical etching” in claim 56 are process limitations in the product claims, which product does not otherwise patentably distinguish over prior art, cannot impart patentability to the product. In re Stephens 145 USPQ 656 (CCPA 1965).

**Response to Arguments**

5. Applicant's arguments with respect to claims 53-59 have been considered but are moot in view of the new ground(s) of rejection.

Art Unit: 2822

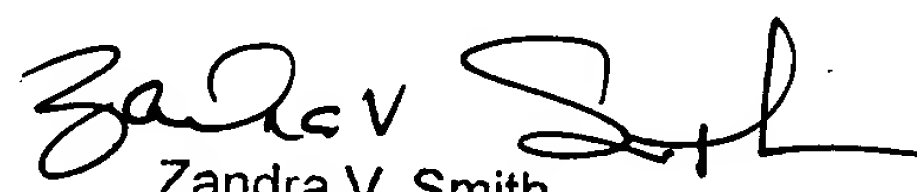
**Contact Information**

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thanh Y. Tran whose telephone number is (571) 272-2110. The examiner can normally be reached on M-F (9-6:30pm).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on (571) 272-2429. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

TYT

  
Zandra V. Smith  
Supervisory Patent Examiner  
14 May 2007